- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- I<sub>off</sub> Feature Supports Partial-Power-Down Mode Operation
- Supports 5-V V<sub>CC</sub> Operation
- Package Options Include Plastic Small-Outline Transistor (DBV, DCK) Packages

### description

This bus buffer gate is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1G125 features a single line driver with a 3-state output. The output is disabled when the output-enable  $(\overline{OE})$  input is high.

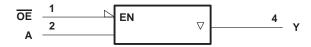
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74LVC1G125 is characterized for operation from -40°C to 85°C.

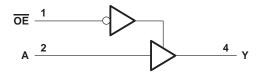
FUNCTION TABLE								
INP	JTS	OUTPUT						
OE	Α	Y						
L	Н	Н						
L	L	L						
н	Х	Z						

### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)





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SN74LVC1G125

SINGLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCES223C - APRIL 1999 - REVISED FEBRUARY 2000

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
	Supplyveltage	Operating	1.65	5.5	v	
VCC	Supply voltage	Data retention only	1.5		v	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
\ <i>\</i>		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		v	
VIH	High-level input voltage	$V_{CC} = 3 V$ to 3.6 V	2		v	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$	$0.7 \times V_{CC}$			
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
Ma		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
VIL	Low-level input voltage	$V_{CC} = 3 \vee \text{to } 3.6 \vee$		0.8	v	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		$0.3 \times V_{CC}$		
VI	Input voltage	-	0	5.5	V	
Vo	Output voltage		0	VCC	V	
		V <sub>CC</sub> = 1.65 V		-4		
	High-level output current	V <sub>CC</sub> = 2.3 V		-8	1	
ЮН		N/		-16	mA	
		V <sub>CC</sub> = 3 V		-24		
		$V_{CC} = 4.5 V$		-32		
		V <sub>CC</sub> = 1.65 V		4		
	Low-level output current	V <sub>CC</sub> = 2.3 V		8		
IOL		N/		16	mA	
		V <sub>CC</sub> = 3 V		24		
		$V_{CC} = 4.5 V$		32		
		$V_{CC}$ = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3 V \pm 0.3 V$	10		ns/V	
		$V_{CC} = 5 V \pm 0.5 V$		5		
Тд	Operating free-air temperature	•	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



## SN74LVC1G125 SINGLE BUS BUFFER GATE WITH 3-STATE OUTPUTS SCES223C – APRIL 1999 – REVISED FEBRUARY 2000

electrical ch	naracteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise no						-	•	

PARAM	IETER	TEST CONDITIONS	Vcc	MIN	TYP <sup>†</sup>	MAX	UNIT	
		I <sub>OH</sub> = -100 μA	1.65 V to 5.5 V	V <sub>CC</sub> -0.1				
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2				
		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9				
Vон		$I_{OH} = -16 \text{ mA}$		2.4			V	
		I <sub>OH</sub> = -24 mA	3 V	2.3				
		I <sub>OH</sub> = -32 mA	2 mA 4.5 V 3.8					
		I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V			0.1		
		I <sub>OL</sub> = 4 mA	1.65 V			0.45		
		I <sub>OL</sub> = 8 mA	2.3 V			0.3		
VOL		I <sub>OL</sub> = 16 mA	2.1			0.4	V	
		I <sub>OL</sub> = 24 mA	3 V			0.55		
		I <sub>OL</sub> = 32 mA	4.5 V			0.55		
	or <mark>OE</mark> puts	VI = 5.5 V or GND	0 to 5.5 V			±5	μA	
l <sub>off</sub>		$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$	0			±10	μA	
loz lcc		$V_{O} = 0$ to 5.5 V	3.6 V			10	μA	
		$V_{I} = 5.5 \text{ V or GND}, \qquad I_{O} = 0$	1.65 V to 5.5 V			10	μA	
ΔICC		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 5.5 V			500	μA	
Ci		$V_I = V_{CC}$ or GND	3.3 V				pF	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> =  $25^{\circ}$ C.

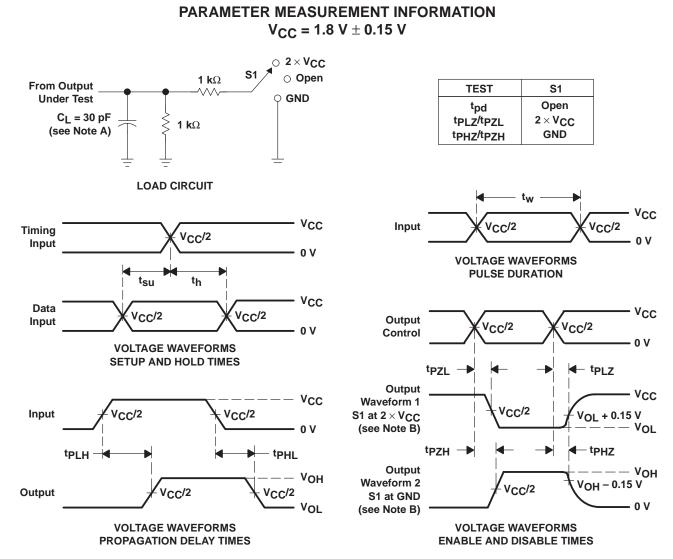
# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

ſ	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> = ± 0.2		= V <sub>CC</sub> ± 0.		= V <sub>CC</sub> ± 0.	= 5 V 5 V	UNIT
		(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	<sup>t</sup> pd	A	Y									ns
	ten	OE	Y									ns
	<sup>t</sup> dis	ŌĒ	Y									ns

## operating characteristics, $T_A = 25^{\circ}C$

Γ		PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> = 5 V	UNIT	
L	FARAIVIETER		TEOTOCINDITIONO	TYP	TYP	TYP	ТҮР		
	C <sub>pd</sub>	Power dissipation capacitance	f = 10 MHz					pF	

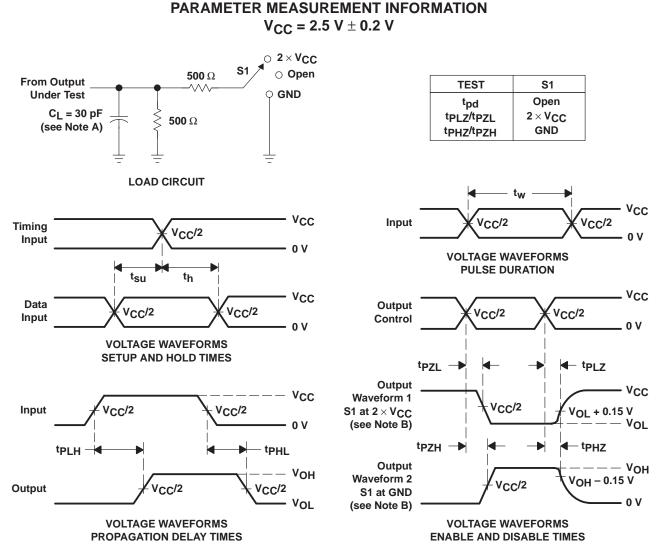




- NOTES: A. CL includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
    C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>Q</sub> = 50 Ω, t<sub>f</sub> ≤ 2 ns, t<sub>f</sub> ≤ 2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLZ and tpHZ are the same as tdis.
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. tpi H and tpHi are the same as tpd.

### Figure 1. Load Circuit and Voltage Waveforms



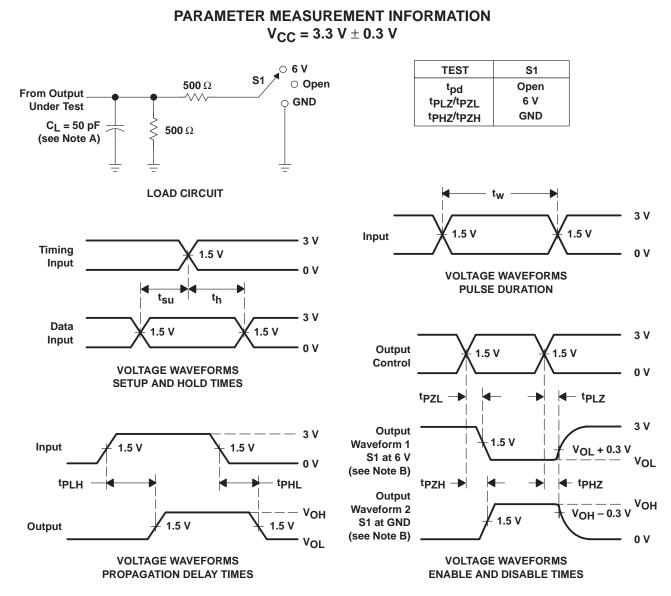


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.

  - E. tpLz and tpHz are the same as tdis. F. tpzL and tpzH are the same as ten.
  - G. tpl H and tpHI are the same as tpd.

## Figure 2. Load Circuit and Voltage Waveforms



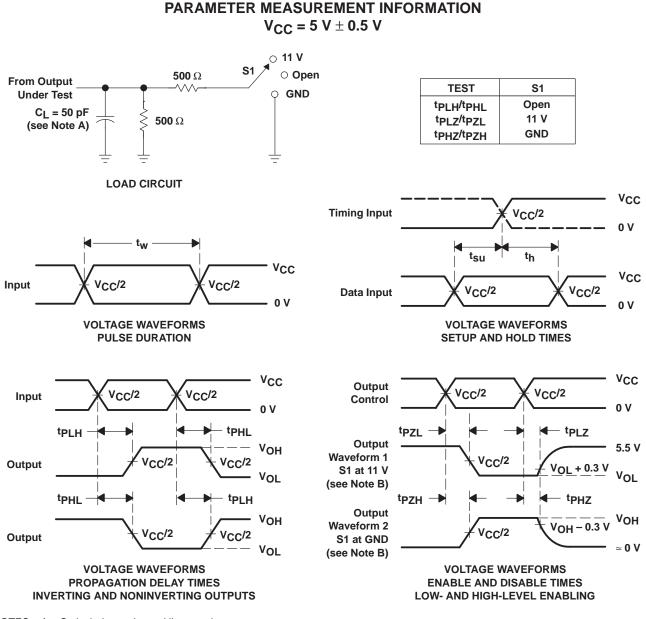


NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tPLH and tPHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms





NOTES: A.  $C_{\mbox{L}}$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>Q</sub> = 50 Ω, t<sub>f</sub> ≤ 2.5 ns. t<sub>f</sub> ≤ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

### Figure 4. Load Circuit and Voltage Waveforms



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